

## *Sensors and Materials*

### **Special Issue on Mechanical and Thermal Reliability of Micro/Nanomaterials**

#### Call for Papers

Owing to the rapid progress of recent semiconductor fabrication technologies, precisely shaped mechanical and electrical components in semiconductor devices and micro-electromechanical systems (MEMS) can be produced. To improve their performance and reliability, the mechanical and thermal properties of structural materials at the micro/nanoscale should be measured experimentally, and then the knowledge obtained in experiments should be reflected in the design of these devices. This special issue will focus on state-of-the-art experimental technologies for measuring the mechanical and thermal properties of silicon and related materials.

#### **Scope:**

- mechanical and thermal properties
- silicon-related materials, metals, and polymers
- reliability of semiconductor devices and MEMS
- experimental technologies
- size effects and process effects

**Submission due date:** August 31, 2018

**Publication date (planned):** First half of 2019

**Journal website:** <http://myukk.org/>

**Guest Editors:** Takahiro Namazu (Aichi Institute of Technology)  
and Shugo Miyake (Kobe City College of Technology)

**Submit to:** 1. Online Manuscript Submission System (<https://myukk-org.ssl-xserver.jp/form/>) or  
2. Email to MYU K.K. ([myukk@myu-inc.jp](mailto:myukk@myu-inc.jp))

#### **(Attention)**

As stated in Instructions to Authors in the Guidelines, the author(s) will be obliged to pay the publication fee upon acceptance of the manuscript for publication (for example, JPY 95040 for 10 pages in *Sensors and Materials* format). If the quality of the English of your manuscript does not satisfy the journal standards, the authors will be subject to a proofreading fee (JPY 10000 or equivalent in USD), which will be charged with the publication fee. We appreciate your understanding on this matter.

If you have any questions, please feel free to contact the editorial staff at the address below.

Editorial Department of *Sensors and Materials*

MYU K.K.

1-23-3-303 Sendagi, Bunkyo-ku, Tokyo 113-0022, Japan

Tel: +81-3-3821-2930, Fax: +81-3-3827-8547

E-mail: [myukk@myu-inc.jp](mailto:myukk@myu-inc.jp)

